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Vishay Siliconix

# Automotive P-Channel 12 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY					
V <sub>DS</sub> (V)	-12				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.00832				
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS}$ = -2.5 V	0.01000				
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS}$ = -1.8 V	0.01430				
I <sub>D</sub> (A)	-25				
Configuration	Single				

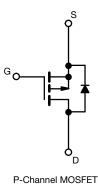
#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>q</sub> and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE



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ORDERING INFORMATION					
Package	SO-8				
Lead (Pb)-free and halogen-free	SQ4153EY (for detailed order number please see <a href="https://www.vishay.com/doc?79771">www.vishay.com/doc?79771</a> )				

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V <sub>DS</sub>	-12	V	
Gate-source voltage		V <sub>GS</sub>	± 8	V	
Continuous drain current a	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	-25		
Continuous drain current <sup>a</sup>	T <sub>C</sub> = 125 °C		-14		
Continuous source current (diode conduction) a		I <sub>S</sub>	-6.5	Α	
Pulsed drain current <sup>b</sup>		I <sub>DM</sub>	-100		
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	-19		
Single pulse avalanche energy	L = 0.1 MH	E <sub>AS</sub>	18	mJ	
Maximum power dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	Б	7.1	W	
waximum power dissipation -	T <sub>C</sub> = 125 °C	$P_{D}$	2.3	VV	
Operating junction and storage temperature	T <sub>J</sub> , T <sub>stq</sub>	-55 to +175	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-ambient	PCB Mount c	$R_{thJA}$	85	°C/W		
Junction-to-foot (drain)		$R_{thJF}$	21	C/VV		

#### Notes

- a. Package limited
- b. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- c. When mounted on 1" square PCB (FR4 material)



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•					
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = -250 \mu A$		-12	-	-	V
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μA		-0.6	-0.9	V
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$		-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -12 V	-	-	-1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -12 V, T <sub>J</sub> = 125 °C	-	-	-50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -12 V, T <sub>J</sub> = 175 °C	-	-	-150	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = -4.5 V	V <sub>DS</sub> ≥ -5 V	-30	-	-	Α
		V <sub>GS</sub> = -4.5 V	I <sub>D</sub> = -14 A	-	0.00510	0.00832	Ω
		V <sub>GS</sub> = -4.5 V	I <sub>D</sub> = -14 A, T <sub>J</sub> = 125 °C	-	-	0.00900	
Drain-source on-state resistance a	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5 V	I <sub>D</sub> = -14 A, T <sub>J</sub> = 175 °C	-	-	0.01100	
		V <sub>GS</sub> = -2.5 V	I <sub>D</sub> = -13 A	-	0.00650	0.01000	
		V <sub>GS</sub> = -1.8 V	I <sub>D</sub> = -12 A	-	0.00940	0.01430	
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = -6 V, I <sub>D</sub> = -10.5 A		-	54	-	S
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>			-	7500	11 000	pF
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = -6 \text{ V}, f = 1 \text{ MHz}$	-	2800	4200	
Reverse transfer capacitance	C <sub>rss</sub>			-	2400	3600	
Total gate charge <sup>c</sup>	$Q_g$			-	101	151	
Gate-source charge <sup>c</sup>	Q <sub>gs</sub>	$V_{GS} = -4.5 \text{ V}$	$V_{GS} = -4.5 \text{ V}$ $V_{DS} = -6 \text{ V}, I_D = -10.5 \text{ A}$		15	-	nC
Gate-drain charge <sup>c</sup>	$Q_{gd}$				45	-	
Gate resistance	$R_g$	f = 1 MHz		1.1	2.2	3.2	Ω
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>			-	31	42	
Rise time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -6 \text{ V}, \text{ R}_{L} = 15 \Omega$ $I_{D} \cong -10.5 \text{ A}, \text{ V}_{GEN} = -4.5 \text{ V}, \text{ R}_{g} = 6 \Omega$		-	168	224	ns
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>			-	310	412	
Fall time <sup>c</sup>	t <sub>f</sub>			-	283	376	
Source-Drain Diode Ratings and Cha	racteristics <sup>b</sup>	•					
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	-100	Α
	V <sub>SD</sub>	$I_F = -10.5 \text{ A}, V_{GS} = 0$					1

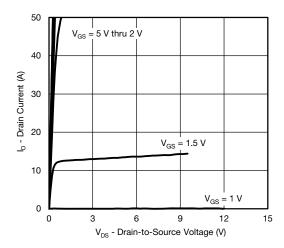
### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

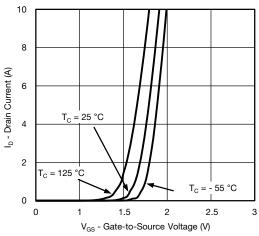
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



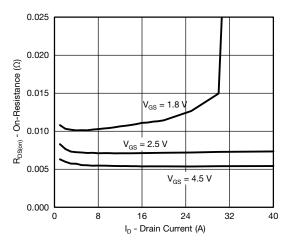
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



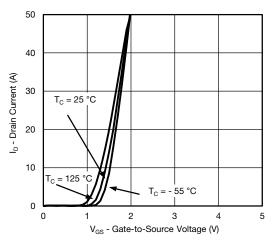
### **Output Characteristics**



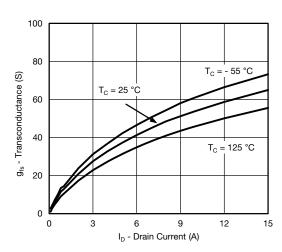
## Transfer Characteristics



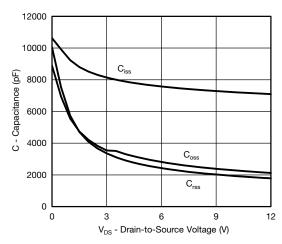
**On-Resistance vs. Drain Current** 



#### **Transfer Characteristics**



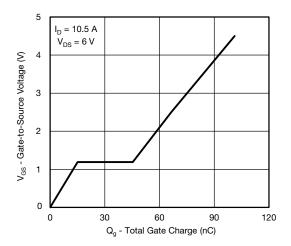
#### Transconductance



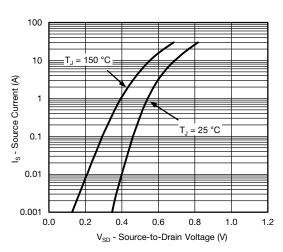
Capacitance



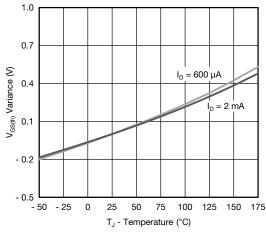
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



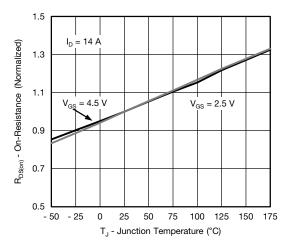
#### **Gate Charge**



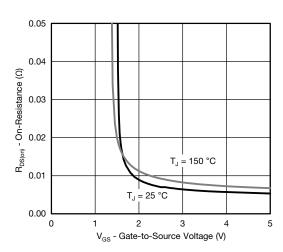
**Source Drain Diode Forward Voltage** 



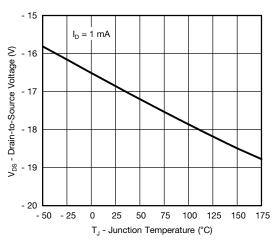
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



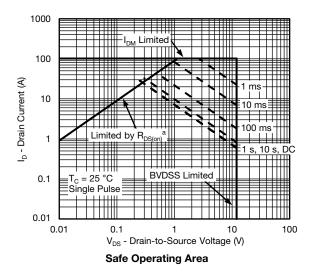
On-Resistance vs. Gate-to-Source Voltage



Breakdown Voltage vs. Junction Temperature

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## **THERMAL RATINGS** ( $T_A = 25 \, ^{\circ}\text{C}$ , unless otherwise noted)

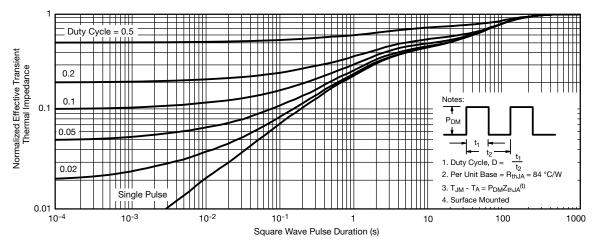


#### Note

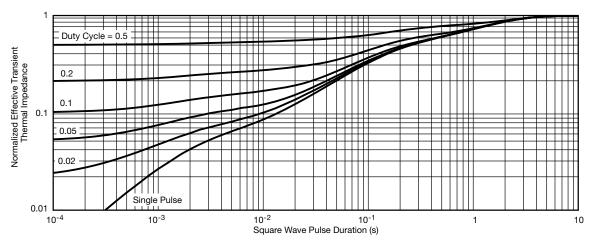
a.  $V_{GS} > \mbox{minimum} \ V_{GS}$  at which  $R_{DS(on)}$  is specified



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?66897">www.vishay.com/ppg?66897</a>.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	MILLIMETERS INCHES		HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050	) BSC	
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I. 11-Sep-06					

DWG: 5498

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## **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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## **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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